SYSTEM CLOCK CHIP

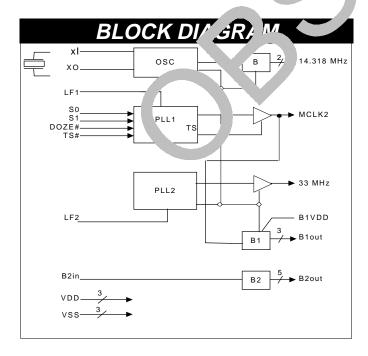
August 29, 1995 Preliminary

CMOS LSI PLL FREQUENCY SYNTHESIZER

PRODUCT FEATURES

- Supports Pentium[™] + M1 asynchronous PCI system board designs
- Integrates system clocks and distribution buffers
- Operates from 5V or 3.3V supply
- Separate B1 buffer VDD supports mixed 5V/3.3V outputs
- Doze and 100μA power down low power operating modes
- 60 mA buffer switching current
- 28 Pin SSOP package for minimum board space

The IMISC497 provides the clocks and the low skew distribution buffers required to drive the Pentium™ CPU and PCI busses. The doze control supports green PC applications by smooth transistioning the CPU clock to it's minimum operating frequency. Power down and output tristate are provided by the TS# input Large buffer drive is provided to handle multiple to ads.



APPLICATIONS

60 mA of switching current is provided on all outputs at B1VDD = VDD = 5V. Under these conditions, the IMISC497 supports up to 10 CI traces and up to 6 CPU traces.

Two 3.3V operating mode sur ort new low voltage components on the C U bus. Operating the B1 buffer at 3.3V (B1VDD) a routing the PU lock through B1 distributes a 3.3' sig. I to the Cropus. The outputs provide 30 mA switching current and the CPU signal can be distrouted to 3 traces with up to 2 planar loads per trace. If core VDD is also operated at 3.3V, all output provide 3.3V signals that can drive TTL or CMOS in the

	F. F. UENCY TABLE									
	S# S1 S0			MCLK2						
				DOZE# = 1	DOZE# = 0					
	1	1 0 0 1 0 1		66.6	33.3					
				50	33.3					
1 1		0	60	33.3						
1	1	1	1	55	33.3					
	0	0	0	PD/LOW	PD/LOW					
	0	1	1	TS	TS					
	0	0	1	40	33.3					

CONNECTION DIAGRAM OSCout [**OSCin** 28 2 $VDD \square$ 27 14.318 Mhz 3 vss 🗆 26 B2in 4 25 33.3 Mhz VSS 24 B1out1 └ MCLK2 6 23 B1VDD └ B2out5 7 22 B1out2 └ B2out4 8 21 B1out3 └ B2out3 9 20 TS# B2out2 10 19 S1 B2out1 11 18 S0 14.318 Mhz 12 17 **AVSS VDD** 13 16 DOZE# LF1 14 15 **AVDD** LF2

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PIN DESCRIPTION

OSCin, OSCout - These pins form an on-chip reference oscillator when connected to terminals of an external parallel resonant crystal (nominally 14.318 MHz). OSCin may also serve as input for an externally generated reference signal.

S0 and **S1** - Standard frequency select inputs. These inputs control the high speed MCLK frequency selection. All these inputs have internal pull-ups. MCLK switches smoothly to changes in these inputs.

The output frequency selection is shown on page 1.

MCLK2 - Aster clock output. Programmable output frequencies can be selected using S0-S1 inputs.

DOZE# - DOZE control pin. When DOZE# is high, the clock chip operates in the standard mode. When this pagoes low output frequencies are switched to the preprogrammed DOZE frequencies. Switching to DOZE frequencies occurs smoothly to allow tracking by CP¹ internal PLL. This pin has an internal pull-up.

B2in - ON-chip buffer input. This is CMC input switches at VDD/2. This pin has a intern put in. ip.

B2out - Buffered outputs of B2 buffer. Switching current and output high level controlled by VDD.

33 MHz - PCI Clock Output

TS# - Logic low on this input fists as clock and B1 buffer outputs if S1 = S0 = Jgic high. LL's a JOSC are stopped to reduce power and all circuit. Is used. If S1 = S0= 0 the outputs are Jamp. How into the power down low (PD/LOW) star instead of a tristate mode. If S1 = 0 and S0=1, an arrive state as show in the frequency table is activated. This pin has an internal pull-up.

14.318 MHz - 1 8 MHz atput. Buffered output of onchip reference oscillator externally provided reference.

LF an F2 - These are the phase detector outputs for the generators hey are single-ended, tristate output for use a loop or signal. A 0.1 μF capacitor to ground should a connected from this pin to form the loop filter. Ground g LF puts PLL in low power mode.

Circuit ground.

VDD - Positive power supply.

AVSS - Analog circuit ground.

AVDD - Analog positive power supply.

B1VDD - 3.3v/5V logic level control for B1 buffer.

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MAXIMUM RATINGS

Voltage Relative to VSS:

Voltage Relative to VDD:

Storage Temperature:

-65°C to +150°

Ambient Temperature:

-55°C to +125°C

Recommended Operating Range:

3V-6V

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage high. than the maximum rated voltages to this circuit for proter operation, Vin and Vout should be consumed to the range:

V′っ 'Vin or Vou ✓DD

Unused ir uts must alway. 'e tied to an appropriate logic vage leva (either VSS or VDD).

ELECTRICAL CHARACTER ISTACS							
Characteristic	Symbol	Min	Тур	Max	Units	Conditions	
Input Low Voltage	V _{IL}	-	-	0.	Vdc	-	
Input High Voltage	V _{IH}	2.0		-	Vdc	TS#, DOZE#, and S0-S1 Inputs	
Input High Voltage	V _{IH}	J.7VDD	-	-	Vdc	B1in and B2in Inputs	
Input Low Current With Pull-up or Pull-down	Į _u .			5 <u>+</u> 50	μΑ	TS#, B1in and B2in, DOZE#, and S0-S2 Inputs	
Input High Current With Pull-up or Pull-down	I _{IH}		-	5 <u>+</u> 50	μΑ	TS#, B1in and B2in, DOZE#, and S0-S2 Inputs	
Output Low Voltage IOH=6mA	V _{OL}	-	-	0.4	Vdc	All Outputs	
Output High Voltage IOH=6mA	ЭН	2.4	-	-	Vdc	All Outputs	
Tri-State Leakage Curre	l _{oz}	-	-	10	μΑ	LF1 and LF2	
Dynamic Supply Current	I _{cc}	-	-	35*	mA	MCLK2 = 50 Mhz	
Static Supply Current	I _{CC} (PD)	-	70	-	μА	TS# = Low, S1 = S0 = High	
Short Circuit Current	I _{SC}	25	-	-	mA	-	
	$VDD = +3.1V \text{ to } +5.5V, TA = 0 \circ C \text{ to } +70 \circ C$						

^{*}For VDD = $5V \pm 10\%$ operation only.

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SWITCHING CHARACTERISTICS						
Characteristic	Symbol	Min	Тур	Max	Units	Condition
Output Rise (0.8V - 2.0V) and Fall (2.0V-0.8V) time All Outputs	t _{TLH} , t _{THL}	-	-	1.5*	ns	∫ pf Load
Output Duty Cycle		40	50/50	45/55	%	Me_ured at 1.5V
MCLK2 to B1out Propagation Delay	t _{PHLH1} , t _{PHL1}	-	3.0*	-	٥	15pf Load Measured at 1.5V
B2Buffer Propagation Delay Bin to Bout	t _{PLH2} , t _{PHL2}	-		-	ns	15 pf load Measured at 1.5V
Buffer out Skew All B1 and B2 Buffer Outputs	t _{SKEW}	-		250	۲	15 pf Load Measured at 1.5V B1in = B2in
ΔPeriod Adjacent Cycles MCLK2	ΔΡ	-	_ 200	-	ps	-
Jitter Absolute MCLK2	T _{jab}	-	- 200		ps	-
Input Rise/Fall Time S0-S1		-		2	μѕ	-
Switching Current Low	I _O (AC)**	-	0*	-	mA	VOL = 1.5V
Switching Current High	он(A))**		50*	-	mA	VOL = 1.5V
VDD = +3.1V to +5.5V, TA = 0°C to + 70°C						

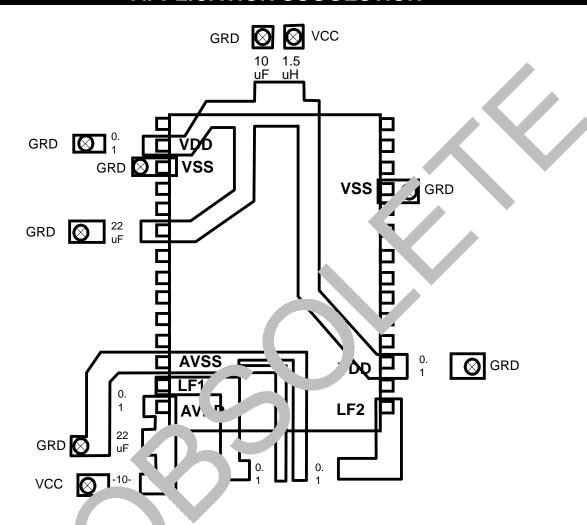
^{*} For VDD = B $^{\prime}$ /DD = +5. $^{\prime}$ /Op. ..ion

^{**} For VDD or IVDD = 5V. educed by 50% at VDD(B2 Buffer) or B1VDD(B1 Buffer) = +3.3V

SYSTEM CLOCK CHIP

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APPLICATION SUGGESTION



NOTES

- 1) LF cap must be connected to AVSS pin, not ground plane. Its connection should not be in the path of current flow from AVSS to GRD.
- 2) Power supply bypass cap (0.1uF) must be positioned close to VDD pins to be effective.
- 3) Top layer traces and filtering to AVDD/AGRD separated from traces to VDD/VSS produce the best performance for IMI clock generators.
- 4) LF caps must be low leakage, such as multilayer ceramic Z5U or X7R material.
- 5) Pin 6 connection changes when mixed 5V/3.3V operation is required.

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APPLICATION SUGGESTION

NOTE 1: Connect Analog Ground to digital Ground through one point only on PC board.

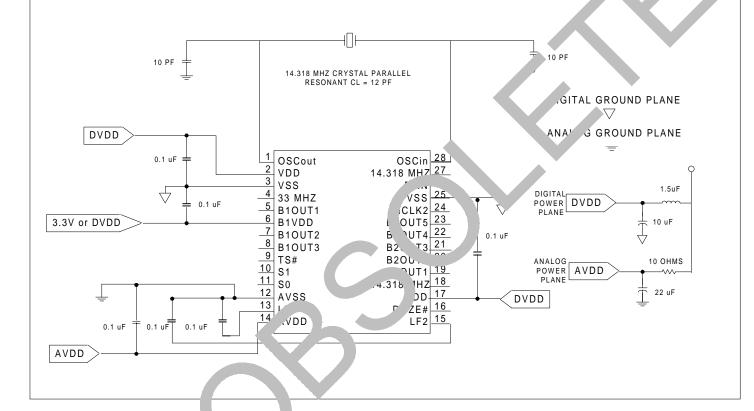
NOTE 2: Caps connected to pins 6, 14, and 17 should be close to their pins.

NOTE 3: Caps on pins 13 and 15 should be connected to AVSS independent of the trace between AVSS and

system ground.

NOTE 4: If VDD at clock generator ramps up more than 100MV DC within a 5 US time period (fror turning disk

drive off, etc.), the values of the DVDD and AVDD filter components should be increased.

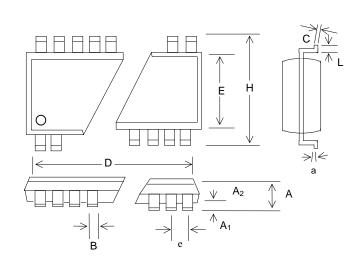


PACKAGE DRAWING AND DIMENSIONS

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28 PIN SSOP OUTLINE DIMENSIONS								
	MIL	LIMETER	RS	INCHES				
SYMBOL	SYMBOL MIN N		MAX	MIN	NOM	MAX		
Α	0.068	0.073	.078	1.73	1.86	1.99		
A ₁	A ₁ 0.002 A2 0.066		0.008	0.05	0.13	0.21		
A2			0 0	1.68	1.73	1.78		
В	0.010	0.012	ა.01	r .s	0.30	0.38		
С	0	0.006	700	0.13	0.15	0.22		
D	0.397	402	0.407	10.0 7	10.2 0	10.33		
	r 205	0.20ა	0.212	5.20	5.30	5.38		
3	0		0.65 BS	SC SC				
H	0.30	0.307	0.311	7.65	7.80	7.90		
а	J.	4°	8°	0°	4°	8°		
L	0.022	0.030	0.037	0.55	0.75	0.95		

ORDERING IN FORMATION							
Part Number	Package Type		Production Flow				
IMISC497xYB	28 PIN SSOF	Cu. Jrcia	al, 0°C to + 70°C				

NOTE: The "x" following the IMI Device ...amber contest the device revision. The ordering part number is formed by a combination of device poer, device resion, package style, and screening as shown below.

Marking: IMI

SC497xYB Date Code Lot #

